

Title (en)

SLURRIES AND METHODS FOR CHEMICAL-MECHANICAL PLANARIZATION OF COPPER

Title (de)

AUFSCHLÄMMUNGEN UND VERFAHREN ZUR CHEMISCH-MECHANISCHEN PLANARISIERUNG VON KUPFER

Title (fr)

SUSPENSIONS AQUEUSES ET PROCEDES POUR LA PLANARISATION CHIMICO-MECANIQUE DU CUIVRE

Publication

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Application

EP 04779276 A 20040727

Priority

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- US 63169803 A 20030730
- US 84671804 A 20040513

Abstract (en)

[origin: WO2005012451A2] The claimed invention involves a novel aqueous slurry for chemical-mechanical planarization that is effective for polishing copper at high polish rates. The aqueous slurry according to the present invention comprises particles of MoO₂ or MoO₃ and an oxidizing agent. A method for polishing copper by chemical-mechanical planarization includes contacting copper with a polishing pad and an aqueous slurry comprising particles of MoO₂ or MoO₃ and an oxidizing agent.

IPC 8 full level

C09G 1/02 (2006.01); **B24B 1/00** (2006.01); **C01G 39/02** (2006.01); **C09G 1/04** (2006.01); **C09K 3/14** (2006.01); **C23F 3/04** (2006.01); **C23F 3/06** (2006.01); **H01L 21/321** (2006.01)

CPC (source: EP KR)

C09G 1/02 (2013.01 - EP); **C09K 3/1409** (2013.01 - EP); **C09K 3/1463** (2013.01 - EP); **C23F 3/06** (2013.01 - EP); **H01L 21/304** (2013.01 - KR); **H01L 21/3212** (2013.01 - EP)

Citation (search report)

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- See references of WO 2005012451A2

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DOCDB simple family (application)

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